*This Action Alert describes an issue which affects product functionality, reliability or safety*

# intel® Action Alert

**AA-0747-2 (Update)**

5200 NE Elam Young Parkway
Hillsboro, OR 97124

February 10, 2005

## Intel® Server Board SE7520BD2 – Heat Sink Fastener Pins Not Fully Inserted

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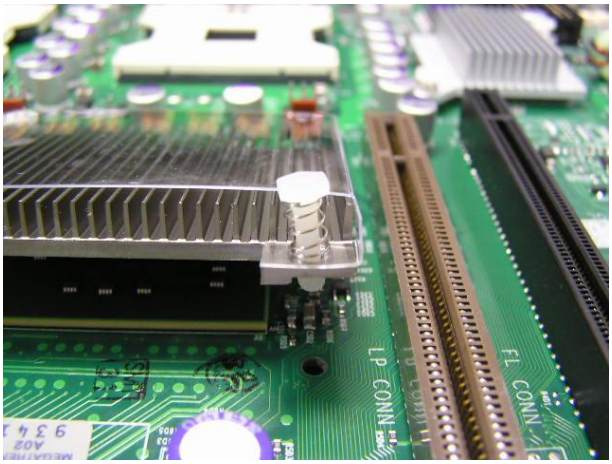
### Products Affected

| | |
|---|---|
| SE7520BD2 – | SE7520BD2 SATA |
| SE7520BD2SCSI – | SE7520BD2 SCSI |
| SE7520BD2V – | SE7520BD2 VALUE |
| BBDVBB – | SE7520BD2 VALUE OEM 10 Pack |
| BBDBBSATA – | SE7520BD2 SATA OEM 10 Pack |
| BBDBBSCS I – | SE7520BD2 SCSI OEM 10 Pack |
| SC5300BD2 – | SE7520BD2V/SC5300BRP |
| SC5300BD2NA – | SE7520BD2V/SC5300BRP with North American power cable |

### Description

Intel has recently been made aware of an issue with some SE7520BD2 server boards where a heat sink retention pin was found disengaged causing the affected heat sink to move from its required position.



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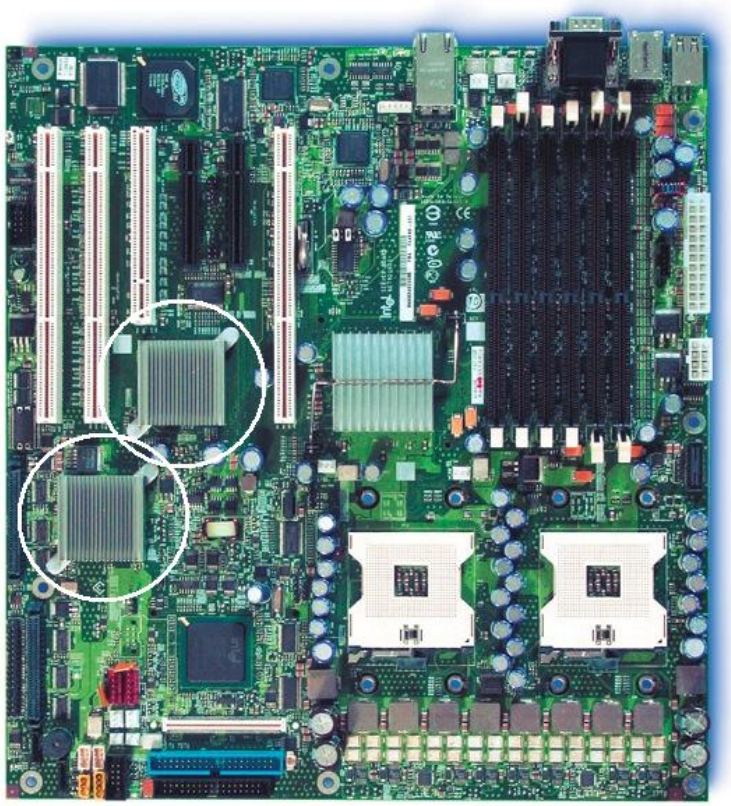
As shown in the following photograph, the Intel Server Board SE7520BD2 has two on-board heat sinks that may be affected by this issue.



Note: SATA only versions, of the SE7520BD2, will only have one affected heat sink. The upper heat sink as pictured above.

**Root Cause**

Through factory process inspection, Intel has determined that inconsistent pressure was being used to insert the heat sink retention pins from one board to the next. Retention pins that were not fully inserted into the baseboard did not have their tabs fully expanded allowing for potential disengagement during shipping due to excessive shock or vibration.

**Corrective Action / Resolution**

For affected products stocked in its warehouses the week of January 17, 2005, Intel has inspected, and where necessary reworked, all boards. All new builds starting from January 18th, 2005 and going forward will have heat sinks mounted using a new process including an end of line visual inspection. Boards assembled with the new process will have a serial number starting at BZBD**504**xxxxx.

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**Recommended Customer Action**

Through continued investigation, Intel has gathered data showing that boards that fall within a serial number range of BZBD**448**xxxxx thru BZBD**451**xxxxx had a higher percentage of occurrence for this issue than boards that fall outside of this serial number range.

Intel recommends that customers with in-house inventories that fall within the specified board serial number range visually screen for possible heat sink pin disengagement and manually check that all heat sink pins are fully engaged. Based on the visual screen results, Intel recommends the following:

1) If a heat sink is found to be fully removed from the baseboard, Intel recommends that the board be returned using the standard RMA process. These boards have a potential of other component damage due to heat sink contact during shipping.
2) If a single heat sink retention pin has disengaged and the heat sink has pivoted from its normal position, Intel recommends that the components around the affected heat sink be visually inspected for damage. If no damage is found, the heat sink can be moved back to its normal position and the loose pin pushed down into place far enough to have its tabs spread open under the baseboard. If component damage is found, the board should be returned using the standard RMA process.
3) If a heat sink pin has disengaged but the heat sink is still in its normal position over the chip, Intel recommends that the pin be pushed back down far enough to have its tabs spread open underneath the baseboard.

Note: Board Serial numbers can be found on the white Product Label on the outside of the shipping box, or on a white label affixed to the baseboard on the board edge next to the IMM Connector.

Please contact your Intel Sales Representative if you require more specific information about this issue.

Enterprise Platforms & Services Division
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